

L Number	Hits	Search Text	DB	Time stamp
1	231958	light-emitting) (light near emitting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:50
2	99034	(light-emitting) (light near emitting) and optical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:51
3	40288	((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:52
4	16721	((((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)) and sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:53
5	12603	(((((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)) and sensor) and (substrate wafer base (auxiliary near carrier)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:55
6	7181	((((((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)) and sensor) and (substrate wafer base (auxiliary near carrier)))) and lens	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:59
8	3459	((((((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)) and sensor) and (substrate wafer base (auxiliary near carrier)))) and lens) and (housing package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:59

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4	16721	((((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)) and sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:53
5	12603	(((((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)) and sensor) and (substrate wafer base (auxiliary near carrier))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:55
6	7181	((((((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)) and sensor) and (substrate wafer base (auxiliary near carrier))) and lens	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 14:59
8	3459	((((((((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)) and sensor) and (substrate wafer base (auxiliary near carrier))) and lens) and (housing package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:00
9	161	(((((((((light-emitting) (light near emitting) and optical) and (recess trench gap cavity opening groove)) and sensor) and (substrate wafer base (auxiliary near carrier))) and lens) and (housing package)) and (spherical near lens)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:01